

# **Device Modeling Report**

COMPONENTS:MAGNETIC CORE  
PART NUMBER:2H04  
MANUFACTURER:FDK



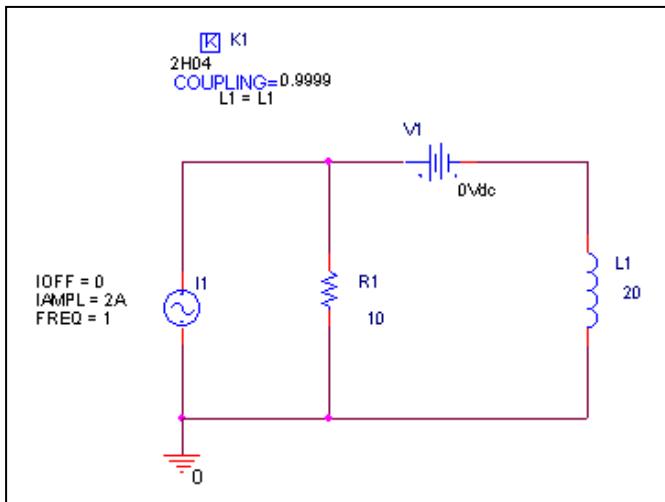
**Bee Technologies Inc.**

## MAGNETIC CORE

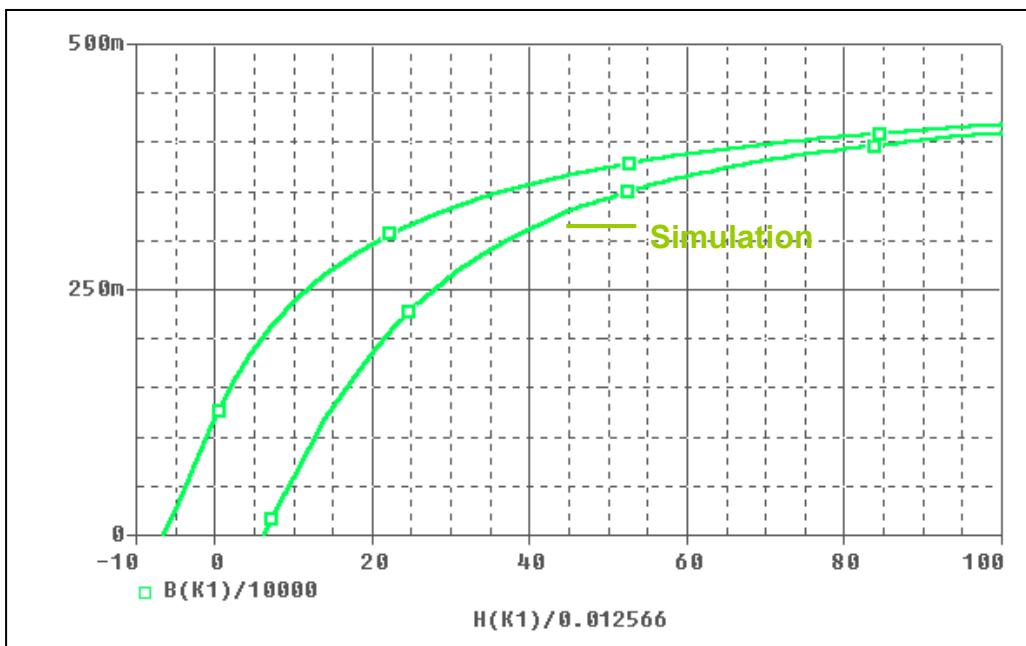
Pspice model parameter	Model description
A	thermal energy parameter
K	domain anisotropy parameter
C	domain flexing parameter
MS	magnetization saturation

## Hysteresis Curve Characteristics

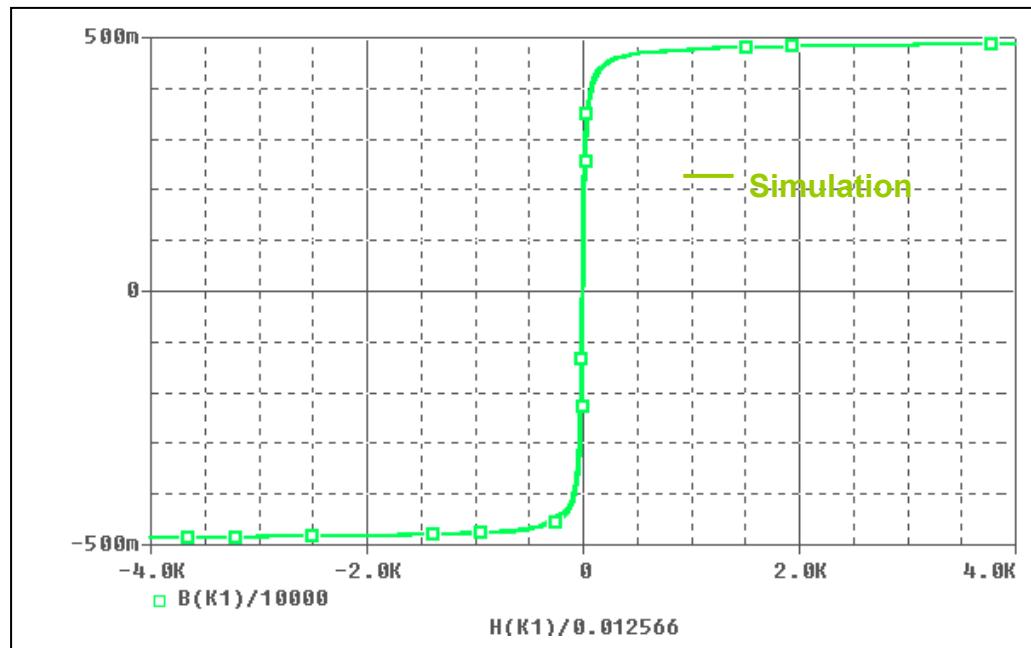
Evaluation Circuit



Simulation result



**Simulation result**



**Comparison Table**

H(A/m)	B(mT) Measurement	B(mT) Simulation	%Error
10	240	237.589	1.005
30	340	332.397	2.236
40	360	355.897	1.140
50	375	374.073	0.247
60	395	387.479	1.904
70	410	397.554	3.036
80	415	405.974	2.175
90	420	412.564	1.770
100	420	419.011	0.235
9	50	50	0.000
30	275	264.194	3.929
40	310	311.081	0.349
50	340	343.424	1.007
60	360	365.072	1.409
70	375	380.705	1.521
80	395	392.734	0.574
90	405	402.255	0.678
100	416	409.846	1.479